

5V, 2-Channels ESD Protection Array

FEATURES

- Meet IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- Meet IEC61000-4-4 (EFT) rating. 40A (5/50ns)
- Protects two directional I/O lines
- Working voltage: 5V
- Pb free version and RoHS compliant
- Packing code with suffix "G" means green compound (halogen-free)

MECHANICAL DATA

- Case: SOT-143 small outline plastic package
- Terminal: Matte tin plated, lead free.
- High temperature soldering guaranteed : 260°C/10s
- Molding compound flammability Rating : UL 94V-0
- Weight: 10 ± 0.5 mg
- Marking code : SL3

APPLICATIONS

- USB Power & Data Line Protection
- I²C Bus Protection
- Video Line Protection
- Microcontroller Input Protections
- T1/E1 Secondary IC Side Protection
- ISDN S/T Interface
- WAN/LAN Equipment
- Ethernet 10BaseT

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Peak Pulse Power (tp=8/20µs waveform)	P _{PP}	200	W	
Peak Pulse Current (tp=8/20µs waveform)	I _{PP}	10	А	
ESD per IEC 61000-4-2 (Air)	V	± 15		
ESD per IEC 61000-4-2 (Contact)	V ESD	± 8	ΓV	
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

PARAMETER		SYMBOL	MIN	MAX	UNIT
Reverse Stand-Off Voltage		V _{RWM}	-	5	V
Reverse Breakdown Voltage	I _R = 1 mA	V _(BR)	6	-	V
Reverse Leakage Current	V _R = 5 V	I _R	-	5	μA
Clamping Voltage	I _{PP} = 1 A	V	-	9.8	v
	I _{PP} = 3 A	v _c	-	17	
Junction Capacitance	V _R =0 V , f = 1.0 MHz	CJ	:	3	pF



SOT-143







RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)















ORDER INFORMATION (EXAMPLE)

TESDB5V0A RBG



Green compound code Packing code Part no.

PACKAGE OUTLINE DIMENSIONS SOT-143



ЫМ	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
А	2.80	3.04	0.110	0.120
В	1.20	1.40	0.047	0.055
С	0.75	0.94	0.030	0.037
D	0.30	0.51	0.012	0.020
E	1.80	2.64	0.071	0.104
F	0.00	0.10	0.000	0.004
G	0.08	0.20	0.003	0.008
Н	0.30	0.60	0.012	0.024
I	0.75	1.15	0.030	0.045
J	2.10	2.64	0.083	0.104
К	0.2 TYP.		0.008 TYP.	

SUGGEST PAD LAYOUT



ЫМ	Unit (mm)	Unit (inch)	
Divi.	Тур.	Тур.	
Z	2.8	0.110	
Х	0.7	0.028	
Y	0.9	0.035	
С	1.9	0.075	
Е	1.0	0.039	

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application.

APPLICATIONS INFORMATION

 \diamond Designed for the protect tow data lines from transient over-voltages by clmaping them to afixed reference

- \bigcirc Data lines are connected at pins 2 and 3
- \diamond The negative reference (REF1) is connected at pin 1 and which should be connected directly to a ground plane (
- \diamond The positive reference (REF2) is connected at pin 4

4 3		
	Pin	Definition
	2, 3	I/O Lines
	1	Ground
1 2	4	VCC





Schematic Diagram for Gigabit Ethernet ESD Protection



♦ Data Line and Power Supply Protection Using VCC

 \Diamond Data Line Protection with Bias and Power Supply Isolation Resistor



 \diamondsuit Data Line Protection Using Internal ESD Diode



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